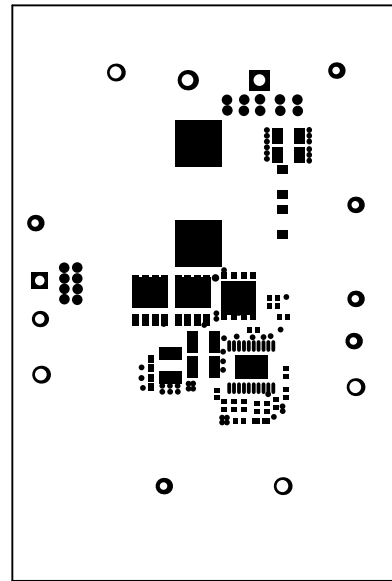
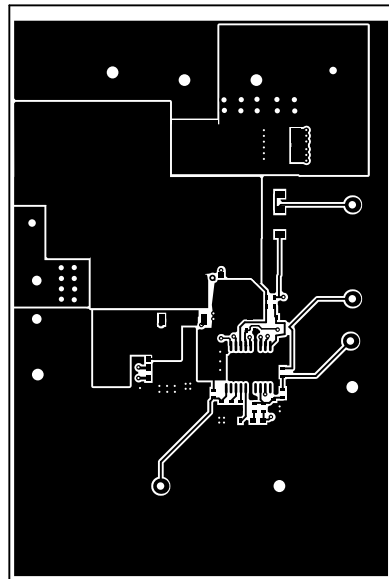


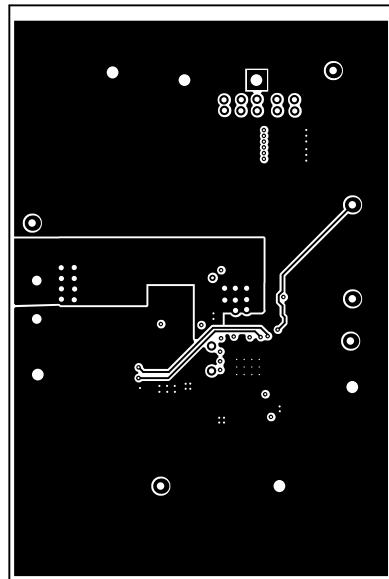
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/20/2015 3:50:00 PM	TEXAS INSTRUMENTS	



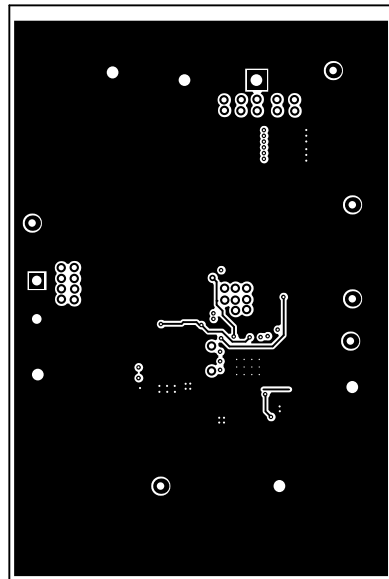
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/20/2015 3:50:01 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 4/20/2015 3:50:01 PM	TEXAS INSTRUMENTS	

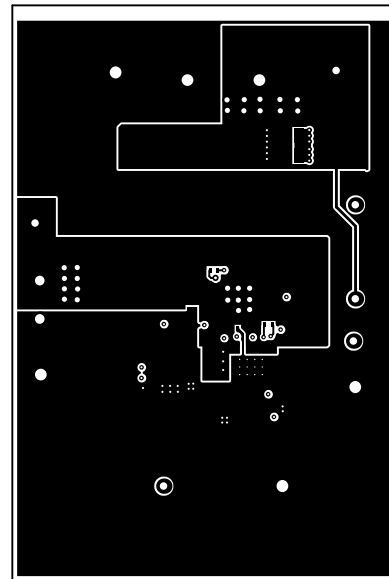


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 4/20/2015 3:50:02 PM	TEXAS INSTRUMENTS	

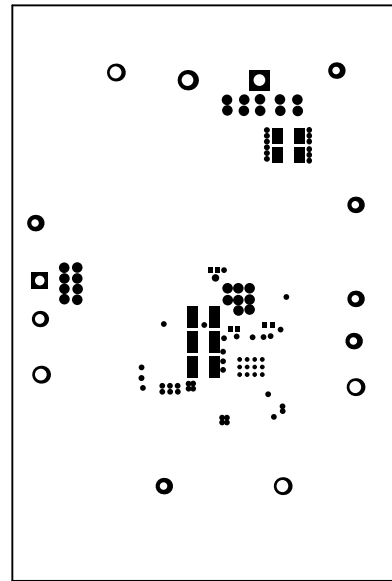


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 4/20/2015 3:50:03 PM	TEXAS INSTRUMENTS	

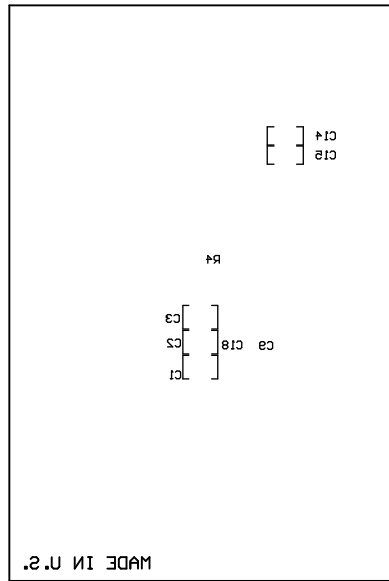
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Signal Layer 1	Copper	2.80mil		
6	Dielectric 3		5.00mil	4.2	
7	Signal Layer 2	Copper	2.80mil		
8	Dielectric 2		10.00mil	4.2	
9	Bottom Layer	Copper	2.80mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



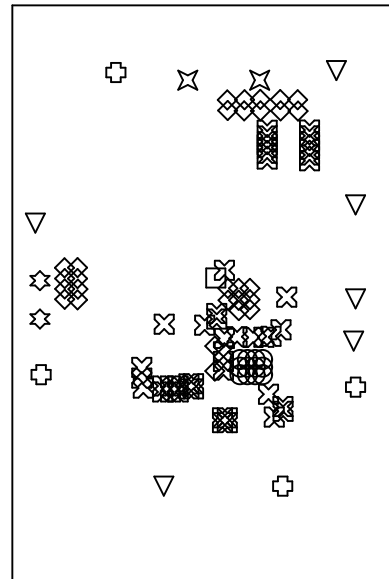
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/20/2015 3:50:04 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 4/20/2015 3:50:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/20/2015 3:50:06 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	12	7.87mil (0.200mm)	PTH	Round
⊗	48	12.00mil (0.305mm)	PTH	Round
□	1	16.00mil (0.406mm)	PTH	Round
◇	28	28.00mil (0.711mm)	PTH	Round
▽	6	40.00mil (1.016mm)	PTH	Round
☆	2	51.18mil (1.300mm)	PTH	Round
⊗	2	62.99mil (1.600mm)	PTH	Round
⊗	4	63.00mil (1.600mm)	PTH	Round
	103 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/20/2015 3:50:07 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10852	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/20/2015 3:50:08 PM	TEXAS INSTRUMENTS	

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